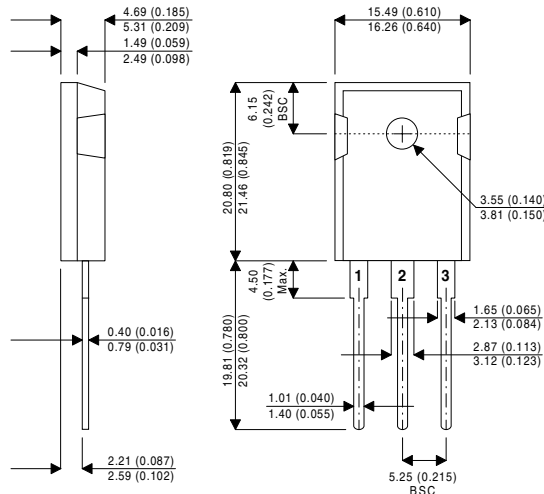


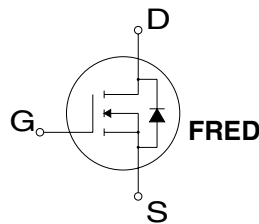
TO-247AD Package Outline.  
Dimensions in mm (inches)



Pin 1 – Gate

Pin 2 – Drain

Pin 3 – Source



**N-CHANNEL  
ENHANCEMENT MODE  
HIGH VOLTAGE  
POWER MOSFETS**

**$V_{DSS}$  800V**

**$I_{D(cont)}$  16A**

**$R_{DS(on)}$  0.560Ω**

- Faster Switching
- Lower Leakage
- 100% Avalanche Tested
- Popular TO-247 Package
- Fast Recovery Diode Onboard

StarMOS is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimises the JFET effect, increases packing density and reduces the on-resistance. StarMOS also achieves faster switching speeds through optimised gate layout.

**ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$  unless otherwise stated)

$V_{DSS}$	Drain – Source Voltage	800	V
$I_D$	Continuous Drain Current	16	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	64	A
$V_{GS}$	Gate – Source Voltage	±30	V
$V_{GSM}$	Gate – Source Voltage Transient	±40	
$P_D$	Total Power Dissipation @ $T_{case} = 25^{\circ}C$	370	W
	Derate Linearly	2.96	W/°C
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	°C
$T_L$	Lead Temperature : 0.063" from Case for 10 Sec.	300	
$I_{AR}$	Avalanche Current <sup>1</sup> (Repetitive and Non-Repetitive)	16	A
$E_{AR}$	Repetitive Avalanche Energy <sup>1</sup>	30	mJ
$E_{AS}$	Single Pulse Avalanche Energy <sup>2</sup>	1300	

**STATIC ELECTRICAL RATINGS** ( $T_{case} = 25^{\circ}C$  unless otherwise stated)

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain – Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	800			V
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{GS} = 0V$ )	$V_{DS} = V_{DSS}$			25	$\mu A$
		$V_{DS} = 0.8V_{DSS}, T_C = 125^{\circ}C$			250	
$I_{GSS}$	Gate – Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			$\pm 100$	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1.0mA$	2		4	V
$I_{D(ON)}$	On State Drain Current <sup>2</sup>	$V_{DS} > I_{D(ON)} \times R_{DS(ON)} \text{ Max}$ $V_{GS} = 10V$	16			A
$R_{DS(ON)}$	Drain – Source On State Resistance <sup>2</sup>	$V_{GS} = 10V, I_D = 0.5 I_D [\text{Cont.}]$			0.56	$\Omega$

**DYNAMIC CHARACTERISTICS**

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input Capacitance	$V_{GS} = 0V$		3700		pF
$C_{oss}$	Output Capacitance	$V_{DS} = 25V$		370		
$C_{rss}$	Reverse Transfer Capacitance	$f = 1MHz$		180		
$Q_g$	Total Gate Charge <sup>4</sup>	$V_{GS} = 10V$		185		nC
$Q_{gs}$	Gate – Source Charge	$V_{DD} = 0.5 V_{DSS}$		16		
$Q_{gd}$	Gate – Drain (“Miller”) Charge	$I_D = I_D [\text{Cont.}] @ 25^{\circ}C$		90		
$t_{d(on)}$	Turn-on Delay Time	$V_{GS} = 15V$		12		ns
$t_r$	Rise Time	$V_{DD} = 0.5 V_{DSS}$		10		
$t_{d(off)}$	Turn-off Delay Time	$I_D = I_D [\text{Cont.}] @ 25^{\circ}C$		43		
$t_f$	Fall Time	$R_G = 1.6\Omega$		10		

**SOURCE – DRAIN DIODE RATINGS AND CHARACTERISTICS**

	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	(Body Diode)			16	A
$I_{SM}$	Pulsed Source Current <sup>1</sup>	(Body Diode)			64	
$V_{SD}$	Diode Forward Voltage <sup>3</sup>	$V_{GS} = 0V, I_S = -I_D [\text{Cont.}]$			1.3	V
$dv / dt$	Peak Diode Recovery <sup>5</sup>				5	V/ns
$t_{rr}$	Reverse Recovery Time	$I_S = -I_D [\text{Cont.}]$ $dI / dt = 100A/\mu s$	$T_J = 25^{\circ}C$		200	ns
			$T_J = 125^{\circ}C$		400	
$Q_{rr}$	Reverse Recovery Charge	$I_S = -I_D [\text{Cont.}]$ $dI / dt = 100A/\mu s$	$T_J = 25^{\circ}C$	0.8		$\mu C$
			$T_J = 125^{\circ}C$	2.9		
$I_{rrm}$	Peak Recovery Current	$I_S = -I_D [\text{Cont.}]$ $dI / dt = 100A/\mu s$	$T_J = 25^{\circ}C$	10		A
			$T_J = 125^{\circ}C$	18		

Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders.

**THERMAL CHARACTERISTICS**

	Characteristic	Min.	Typ.	Max.	Unit
$R_{\theta JC}$	Junction to Case			0.34	°C/W
$R_{\theta JA}$	Junction to Ambient			40	

- 1) Repetitive Rating: Pulse Width limited by maximum junction temperature.
- 2) Starting  $T_J = 25^\circ\text{C}$ ,  $L = 10.16\text{mH}$ ,  $R_G = 25\Omega$ , Peak  $I_L = 16\text{A}$
- 3) Pulse Test: Pulse Width  $< 380\mu\text{S}$ , Duty Cycle  $< 2\%$
- 4) See MIL-STD-750 Method 3471
- 5)  $I_{SS} - I_D [\text{Cont.}] \text{ di/st} = 100\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DSS}$ ,  $T_j \leq 150^\circ\text{C}$ ,  $R_G = 2.0 \Omega$ ,  $V_R = 200\text{V}$



**CAUTION** — Electrostatic Sensitive Devices. Anti-Static Procedures Must Be Followed.

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